

DIIPM equipped with a silicon chip : Large DIIPM+ reliability test results

Table 1. Reliability test results

Test Items 試験項目	Test conditions 試験条件	Number of samples 試料数	Number of failures 故障数
Resistance to soldering heat はんだ耐熱性	Solder temperature : 260°C Time : 10seconds	5	0
Solderability はんだ付け性	Preheating : 100°C Solder temperature : 250°C Time : 10seconds	5	0
Temperature cycle 温度サイクル	-40°C~125°C 30minutes each 100cycles	5	0
Terminal strength(pull) 端子強度 (引張り)	Control terminal : Weight 10N Power terminal : Weight 40N 10seconds	5	0
Terminal strength(Bending) 端子強度 (曲げ)	Weight 10N 90deg. Bend 2times	5	0
Mounting torque 締付けトルク	Mounting screw : M4 1.47N·m	5	0
High temperature storage 高温保存	T _a =125°C 1000hours	5	0
Temperature humidity storage 高温高湿保存	T _a =60°C RH=90% 1000hours	5	0
High-Temperature Reverse-Bias 高温逆バイアス (Inverter-part)	T _j =150°C V _{CE} =0.85*V _{CES} 1000hours	5	0
High-Temperature Reverse-Bias 高温逆バイアス (Converter-part)	T _a =125°C V _{CE} =0.85*V _{CES} 1000hours	5	0
Intermittent operating life 断続動作	ΔT _j =100°C 5000cycles	5	0

Table 2. Failure criteria

Parameter 測定項目	Measurement conditions 測定条件	Criteria for failure 故障判定基準		Remarks 備考
		Lower Limit 下限	Upper Limit 上限	
I _{CEs}	V _{CE} =Rated voltage	—	U.S.L.×2.0	
V _{EC}	-I _C =Rated current	—	U.S.L.×1.2	
V _{CE(sat)}	I _C =Rated current, V _D =V _{DB} =15V, V _{IN} =5V	—	U.S.L.×1.2	
I _D	V _D =15V, V _{IN} =0V	—	U.S.L.×2.0	
I _{DB}	V _D =V _{DB} =15V, V _{IN} =0V	—	U.S.L.×2.0	
I _{RRM}	V _R =Rated voltage	—	U.S.L.×2.0	
V _F	I _F =Rated current	—	U.S.L.×1.2	
Dielectric withstand	2500Vrms, Sinusoidal, AC 1 minute, all connection pins to heat-sink plate	Break down		

Note : The reliability tests are performed the representative products for the product group.
The measurement items of each test are selected according to our standards.
The symbols in the table are as follows. U.S.L. : Upper Specification Limit

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